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RESISTOR NETWORKS, THICK FILM


ESCC Generic Specification No. 4005

ISSUE 1

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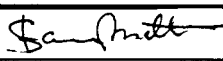
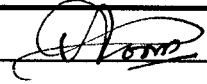
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RESISTOR NETWORKS, THICK FILM

ESA/SCC Generic Specification No. 4005



**space components
coordination group**

Issue/Rev.	Date	Approved by	
		SCCG Chairman	ESA Director General or his Deputy
Issue 4	April 1999		



DOCUMENTATION CHANGE NOTICE

Rev. Letter	Rev. Date	Reference	CHANGE Item	Approved DCR No.
		<p>This Issue supersedes Issue 3 and incorporates all modifications defined in Revisions 'A', 'B' and 'C' to Issue 3 and the changes agreed in the following DCR's:-</p> <p>Cover page DCN</p> <p>Para. 8.2.1 : New second sentence added to last paragraph</p> <p>Para. 10.1.2.1 : Item (b), "PDA figure and" deleted from text : Item (c) rewritten</p> <p>Para. 10.1.3.1 : Item (a), "(including PDA figure)" deleted</p>		<p>None None 21119 21111 21119 21119</p>

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**1. INTRODUCTION****1.1 SCOPE**

This specification defines the general requirements for the qualification approval, procurement, including lot acceptance testing, and delivery of Resistor Networks, Thick Film, for space application.

This specification contains the appropriate inspection and test schedules and also specifies the data documentation requirements.

1.2 APPLICABILITY

This specification is primarily applicable to the granting of qualification approval to a component in accordance with ESA/SCC Basic Specification No. 20100 and the procurement of such components from qualified Manufacturers.

2. APPLICABLE DOCUMENTS

The following documents form part of, and shall be read in conjunction with, this specification. The relevant issues shall be those in effect on the date of placing the purchase order.

2.1 ESA/SCC SPECIFICATIONS

No. 20100, Requirements for the Qualification of Standard Electronic Components for Space Application.

No. 20400, Internal Visual Inspection.

No. 20500, External Visual Inspection.

No. 20600, Preservation, Packaging and Despatch of SCC Electronic Components.

No. 20900, Radiographic Inspection.

No. 21300, Terms, Definitions, Abbreviations, Symbols and Units.

No. 21700, General Requirements for the Marking of SCC Components.

No. 22800, ESA/SCC Non-conformance Control System.

No. 23500, Requirements for Lead Materials and Finishes for Components for Space Application.

No. 24600, Minimum Quality System Requirements.

No. 24800, Resistance to Solvents of Marking, Materials and Finishes.

With the exception of ESA/SCC Basic Specifications Nos. 20100, 21700, 22800 and 24600, where Manufacturers' specifications are equivalent to, or more stringent than, the ESA/SCC Basic Specifications listed above, they may be used in place of the latter, subject to the approval of the appropriate Qualifying Space Agency.

Such replacements shall be clearly identified in the applicable Process Identification Document (P.I.D.) and listed in an appendix to the appropriate Detail Specification.

Unless otherwise stated herein, references within the text of this specification to "the Detail Specification" shall mean the relevant ESA/SCC Detail Specification.



2.2 OTHER (REFERENCE) DOCUMENTS

IEC Publication No. 68, Basic Environmental Testing Procedures.

IEC Publication No. 115, Fixed Resistors for Use in Electronic Equipment.

IEC Publication No. 410, Sampling Plans and Procedures for Inspection by Attributes or, MIL-STD-105, Sampling Procedures and Tables for Inspection by Attributes.

IEC Publication No. 440, Method of Measurement of Non-linearity in Resistors.

MIL-STD-414, Sampling Procedures and Tables for Inspection by Variables for Percent Defective.

MIL-STD-883, Test Methods and Procedures for Microelectronics.

ESA PSS-01-702, A Thermal Vacuum Test for the Screening of Space Materials.

2.3 ORDER OF PRECEDENCE

For the purpose of interpretation and in case of conflict with regard to documentation, the following order of precedence shall apply:-

- (a) ESA/SCC Detail Specification.
- (b) ESA/SCC Generic Specification.
- (c) ESA/SCC Basic Specification.
- (d) Other documents, if referenced herein.

3. TERMS, DEFINITIONS, ABBREVIATIONS, SYMBOLS AND UNITS

The terms, definitions, abbreviations, symbols and units specified in ESA/SCC Basic Specification No. 21300 shall apply.

4. REQUIREMENTS

4.1 GENERAL

The test requirements for qualification approval of a component shall comprise final production tests (see Chart II), burn-in and electrical measurements to testing level 'B' (see Chart III) and qualification testing (see Chart IV).

The test requirements for procurement of components shall comprise final production tests (Chart II), burn-in and electrical measurements to testing level 'B' or 'C' as required (Chart III) together with, when applicable, a level of lot acceptance testing (see Chart V) to be specified by the Orderer.

If a Manufacturer elects to eliminate a final production test by substituting an in-process control or statistical process control procedure, the Manufacturer is still responsible for delivering components that meet all of the performance, quality and reliability requirements defined in this specification and the Detail Specification.

4.1.1 Specifications

For qualification approval, procurement (including lot acceptance testing) and delivery of components in conformity with this specification, the specifications listed in Section 2 of this document shall apply in total unless otherwise specified herein or in the Detail Specification.

4.1.2 Conditions and Methods of Test

The conditions and methods of test shall be in accordance with this specification, the ESA/SCC Basic Specifications referenced herein and the Detail Specification.



4.1.3 Manufacturer's Responsibility for Performance of Tests and Inspections

The Manufacturer shall be responsible for the performance of tests and inspections required by the applicable specifications. These tests and inspections shall be performed at the plant of the Manufacturer of the components unless it is agreed by the Qualifying Space Agency prior to commencing qualification testing, or procurement, to use an approved external facility.

4.1.4 Inspection Rights

The Qualifying Space Agency (for qualification approval or for a procurement) reserves the right to monitor any of the tests and inspections scheduled in the applicable specifications.

4.1.5 Pre-encapsulation or Pre-coating Inspection

The Manufacturer shall notify the Orderer at least 2 working weeks before the commencement of pre-encapsulation or pre-coating inspection.

The Orderer shall indicate immediately whether or not he intends to witness the inspection.

4.2 QUALIFICATION APPROVAL REQUIREMENTS ON A MANUFACTURER

To obtain and maintain the qualification approval of a component, or family of components, a Manufacturer shall satisfy the requirements of ESA/SCC Basic Specification No. 20100.

4.3 DELIVERABLE COMPONENTS

Components delivered to this specification shall be processed and inspected in accordance with the relevant Process Identification Document (P.I.D.). Each delivered component shall be traceable to its production lot. Components delivered to this specification shall have completed satisfactorily all tests to the testing level and lot acceptance level specified in the purchase order (see Para. 4.3.2).

ESA/SCC qualified components delivered to this specification shall be produced from lots that are capable of passing all tests, and sequences of tests, that are defined in Charts IV and V. The Manufacturer shall not knowingly supply components that cannot meet this requirement. In the event that, subsequent to delivery and prior to operational use, a component is found to be in a condition such that it could not have passed these tests at the time of manufacture, this shall be grounds for rejection of the delivered lot.

Components failing inspections and tests of the higher testing level (i.e level 'B') shall not be supplied against any order for components of the lower testing level.



4.3.1 Lot Failure

Lot failure may occur during final production tests (Chart II), burn-in and electrical measurements (Chart III), qualification testing (Chart IV) or lot acceptance testing (Chart V).

Should such failure occur, the non-conformance procedure shall be initiated in accordance with ESA/SCC Basic Specification No. 22800.

Should such failure occur during procurement, the Manufacturer shall notify the Orderer by telex within 2 working days, giving details of the number and mode of failure and the suspected cause.

In the case where qualification approval has been granted to the component, he shall, at the same time by the same means, inform the Qualifying Space Agency in order that the latter may consider its implications.

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No further testing shall be performed on the failed components except on instruction from the Orderer. The Orderer shall inform the Manufacturer and the Qualifying Space Agency within 2 working days of receipt of the telex, by the same means, what action shall be taken.

In the case when lot failure occurs during qualification testing, the Manufacturer shall immediately notify the appropriate Qualifying Space Agency who will define a course of action to be followed. No further testing shall be performed on the failed components.

4.3.2 Testing and Lot Acceptance Levels

This specification defines 2 levels of testing severity which are designated by the letters 'B' and 'C' (see Chart I) and 3 levels of lot acceptance testing (see Chart V).

The lot acceptance levels are designated 1, 2 and 3 and are comprised of tests as follows:-

- Level 3 (LA3) - Electrical Subgroup.
- Level 2 (LA2) - Endurance Subgroup
plus Electrical Subgroup.
- Level 1 (LA1) - Environmental and Mechanical Subgroup
plus Endurance Subgroup
plus Electrical Subgroup.

The required testing level and lot acceptance level shall both be specified in a purchase order.

4.4 MARKING

All components procured and delivered to this specification from a source qualified according to ESA/SCC Basic Specification No. 20100 shall be marked in accordance with ESA/SCC Basic Specification No. 21700. Thus, they shall bear the ESA symbol to signify their conformance to the ESA/SCC qualification approval requirements and full compliance with the requirements of this specification and the Detail Specification.

Components procured from sources which are not ESA/SCC qualified, provided that they fully comply with the procurement requirements of this specification and the Detail Specification, may bear the SCC marking **with the exception of the ESA symbol.**

4.5 MATERIALS AND FINISHES

All non-metallic materials and finishes, that are not within a hermetically sealed enclosure, of the components specified herein shall meet the outgassing requirements as outlined in ESA PSS-01-702.

Specific requirements for materials and finishes are specified in the Detail Specification.

5. PRODUCTION CONTROL

5.1 GENERAL

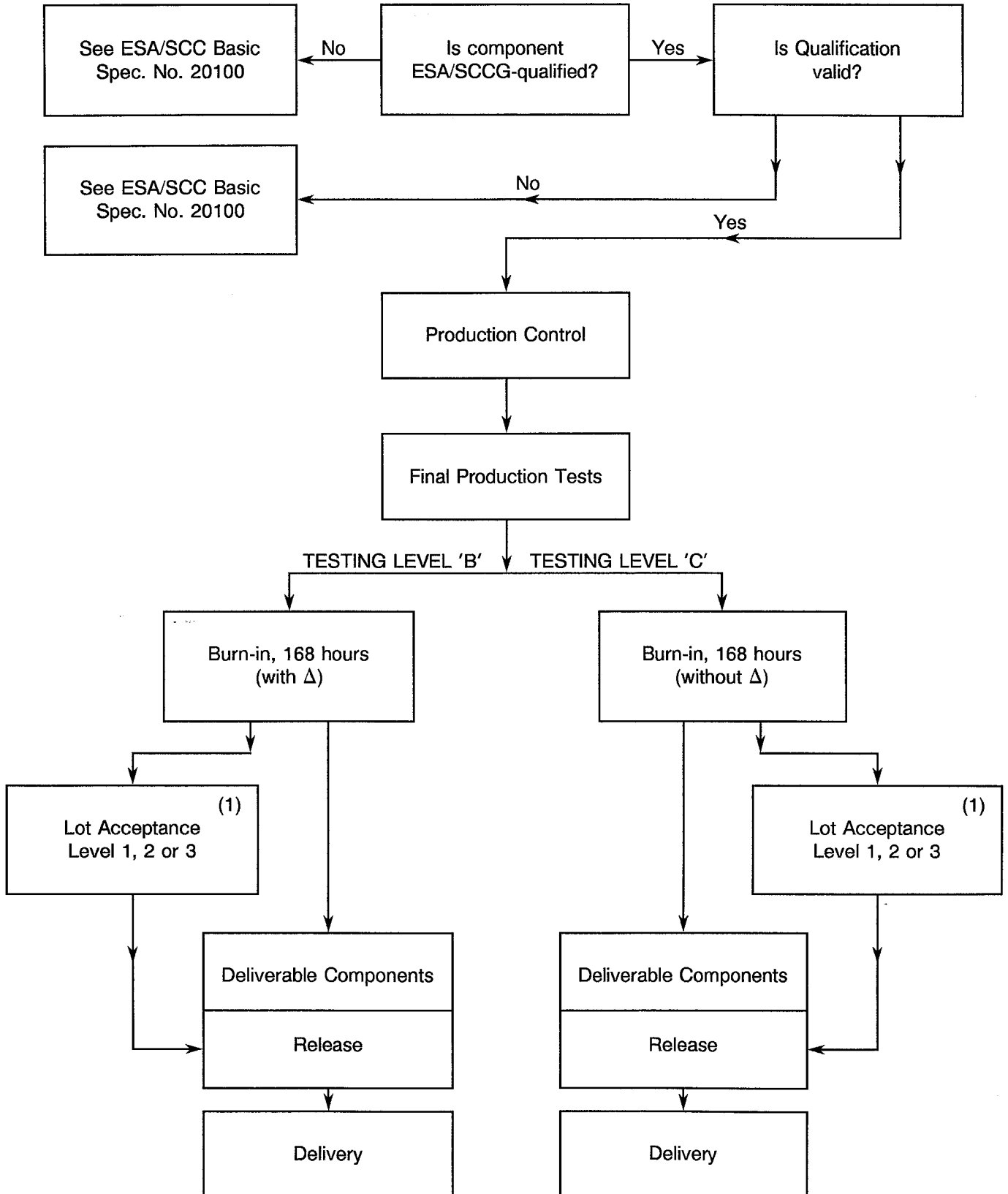
The minimum requirements for production control, which are equally applicable to procurement, are defined in ESA/SCC Basic Specification No. 20100, Paras. 5.1 and 5.2.

5.2 SPECIAL IN-PROCESS CONTROLS

Where applicable, special in-process controls shall apply as specified in the Detail Specification.



CHART I - TESTING LEVELS



NOTES

1. When applicable.

**6. FINAL PRODUCTION TESTS****6.1 GENERAL**

Unless otherwise specified in the Detail Specification, all components used for qualification testing and all components for delivery, including those submitted to lot acceptance tests, shall be subjected to tests and inspections in accordance with Chart II.

Unless otherwise specified in the Detail Specification, the tests shall be performed in the order shown.

Any components that do not meet these requirements shall be removed from the lot and at no future time be re-submitted to the requirements of this specification.

6.2 TEST METHODS AND CONDITIONS

The applicable test methods and conditions are specified in the paragraphs referenced in Chart II of this specification.

6.3 DOCUMENTATION

Documentation of final production test data shall be in accordance with the requirements of Para. 10.6 of this specification.

7. BURN-IN AND ELECTRICAL MEASUREMENTS**7.1 GENERAL**

Unless otherwise specified in the Detail Specification, all components used for qualification testing and all components for delivery, including those submitted to lot acceptance tests, shall be subjected to tests and inspections in accordance with Chart III.

Unless otherwise specified in the Detail Specification, the tests shall be performed in the order shown.

The applicable test methods and conditions are specified in the paragraphs referenced in Chart III.

Components of testing level 'B' shall be serialised prior to the tests and inspections.

7.1.1 Conditions of Test

The conditions for burn-in shall be as shown in Table 5 of the Detail Specification.

Unless otherwise specified in the Detail Specification, components of both Levels 'B' and 'C' shall be subjected to a total burn-in period of 168 hours.

7.1.2 Data Points

For components of testing level 'B', undergoing a total burn-in period of 168 hours, the data points for parameter drift measurement shall be 0 hours (initial) and 168 (+24 - 0) hours (final).

For components of testing level 'C', undergoing a total burn-in period of 168 hours, the data point for post-burn-in electrical measurements shall be 168 (+24 - 0) hours.



7.2. FAILURE CRITERIA

7.2.1 Parameter Drift Failure

The acceptable delta limits are shown in Table 4 of the Detail Specification. A component of testing level 'B' shall be counted as a parameter drift failure if the changes during burn-in are larger than the delta (Δ) values specified.

7.2.2 Parameter Limit Failure

A component shall be counted as a limit failure if one or more parameters exceed the limits shown in Tables 2 or 3 of the Detail Specification.

Any component which exhibits a limit failure prior to the burn-in sequence shall be rejected and not counted when determining lot rejection.

7.2.3 Other Failures

A component shall be counted as a failure in any of the following cases:

- Mechanical failure.
- Handling failure.
- Lost component.

7.3 FAILED COMPONENTS

A component shall be considered as a failed component if it exhibits one or more of the failure modes described in Para. 7.2 of this specification.

7.4 LOT FAILURE

In case of lot failure, the Manufacturer shall act in accordance with the requirements of Para. 4.3.1 of this specification.

7.4.1 Lot Failure during 100% Testing

If the number of components failed on the basis of the failure criteria described in Para. 7.2 exceeds 5% (rounded upwards to the nearest whole number) of the number of components submitted to burn-in and electrical measurements, the lot shall be considered as failed.

If a lot is composed of groups of components of one family defined in one ESA/SCC Detail Specification, but separately identifiable for any reason, then the lot failure criteria shall apply separately to each identifiable group.

7.4.2 Lot Failure during Sample Testing

A lot shall be considered as failed if the number of allowable failures during sample testing, in accordance with General Inspection Level II of IEC Publication No. 410 or MIL-STD-105 and the applicable AQL as specified in the Detail Specification, is exceeded.

In the case where an LTPD to MIL-STD-414 is specified in the Detail Specification, a lot shall be considered as failed if the number of failures allowed is exceeded (see Annex I for LTPD Sampling Plan).

If a lot failure occurs in either case, a 100% testing may be performed with the lot failure criteria given in Para. 7.4.1.

7.5 DOCUMENTATION

Data documentation of burn-in and electrical measurements shall be in accordance with Para. 10.7 of this specification.



8. QUALIFICATION APPROVAL AND LOT ACCEPTANCE TESTS

8.1 QUALIFICATION TESTING

8.1.1 General

Qualification testing shall be in accordance with the requirements of Chart IV of this specification. The tests to Chart IV shall be performed on the specified sample, chosen at random from components which have successfully passed the tests in Charts II and III for Testing Level 'B'. This sample constitutes the qualification test lot.

The qualification test lot is divided into subgroups of tests and all components assigned to a subgroup shall be subjected to all of the tests in that subgroup, in the sequence shown.

The applicable test requirements are detailed in the paragraphs referenced in Chart IV.

The conditions governing qualification testing are given in ESA/SCC Basic Specification No. 20100, Para. 5.3 and, for the extension or renewal of qualification approval, in Paras. 6.3 and 6.4.

8.1.2 Distribution within the Qualification Test Lot

A minimum sample of 90 components shall be submitted to qualification testing (Chart IV). The distribution within the sample shall be as follows:-

First case

If the critical resistance is within the range to be qualified:

- 1/3 of the lot with the critical resistance value.
- 1/3 of the lot with the lowest resistance value.
- 1/3 of the lot with the highest resistance value.

Second case

If the critical resistance is outside the range to be qualified:

- 1/3 of the lot with the lowest resistance value.
- 1/3 of the lot with the highest resistance value.
- 1/3 of the lot with the resistance value in the middle of the range.

The selected distribution shall be agreed with the Qualifying Space Agency.

8.2 LOT ACCEPTANCE TESTING

8.2.1 General

The sample sizes of the 3 lot acceptance levels are specified in Chart V. All components assigned to a subgroup shall be subjected to all of the tests of that subgroup in the sequence shown.

The tests to Chart V shall be performed on the specified sample which shall have been chosen, whenever possible, at random from the proposed delivery lot (but see Para. 8.2.3(b)).

The applicable test requirements are detailed in the paragraphs referenced in Chart V.

As a minimum for procurement of non-qualified components, lot acceptance level 3 shall apply. For procurement of qualified components, lot acceptance testing shall be performed if specified in a purchase order. Procurement lots ordered with a lot acceptance test level shall be delivered only after successful completion of lot acceptance testing.



8.2.2 Distribution within the Sample for Lot Acceptance Testi

Where a Detail Specification covers a range or series of components that are considered similar, then it may be necessary that the sample for lot acceptance testing be comprised of component types so selected that they adequately represent all of the various mechanical, structural and electrical peculiarities of the procured range or series.

The distribution of the component types will normally vary from procurement to procurement and shall be as specified by the Orderer, following as closely as possible the requirements prescribed in Para. 8.1.2. of this specification.

8.2.3 Lot Acceptance Level 3 Testing (LA3)

Lot acceptance level 3 tests are designated as the electrical subgroup and comprise electrical measurements of characteristics and tests to prove the assembly capability of the component. For LA3 testing, the following requirements and conditions shall apply:-

- (a) LA3 testing shall be performed by the Manufacturer's quality assurance personnel using dedicated quality assurance equipment whenever possible. LA3 testing shall not be a repetition of routine measurements made by production personnel during final production tests and burn-in and electrical measurements.
- (b) When tests to Tables 2 and 3 of the Detail Specification have been performed on a sample basis, then the components for LA3 testing shall be selected from this sample.
- (c) The electrical measurements for LA3 are considered to be non-destructive and therefore components so tested may form part of the delivery lot.
- (d) The solderability and terminal strength tests are considered to be destructive and therefore components so tested shall not form part of the delivery lot. Post-burn-in electrical rejects may be used for these tests.
- (e) When required in the purchase order, the Manufacturer shall notify the Orderer at least 2 working weeks before the commencement of LA3 testing. The Orderer shall indicate immediately whether or not he intends to witness the tests.

8.2.4 Lot Acceptance Level 2 Testing (LA2)

Lot acceptance level 2 testing shall comprise the tests for LA3 (electrical subgroup) plus tests on an endurance subgroup. For the electrical subgroup, the requirements and conditions as for LA3 (see Para. 8.2.3) shall apply.

For the endurance subgroup, the following shall apply:-

- (a) Components of testing level 'C', selected for the endurance subgroup, shall be serialised prior to the tests.
- (b) The tests in this subgroup are considered to be destructive and therefore components (of testing level 'B' or 'C') so tested shall not form part of the delivery lot.

8.2.5 Lot Acceptance Level 1 Testing (LA1)

Lot acceptance level 1 testing shall comprise the tests for LA3 (electrical subgroup) and LA2 (endurance subgroup) plus tests on an environmental and mechanical subgroup. For the electrical and endurance subgroups, the requirements and conditions for LA3 (see Para. 8.2.3) and LA2 (see Para. 8.2.4) respectively shall apply.

For the environmental subgroup, the following shall apply:-

- (a) Components of testing level 'C', selected for the environmental subgroup, shall be serialised prior to the tests.
- (b) The tests in this subgroup are considered to be destructive and therefore components (of testing level 'B' or 'C') so tested shall not form part of the delivery lot.



8.3 FAILURE CRITERIA

The following criteria shall apply to qualification testing and to lot acceptance testing.

8.3.1 Environmental and Mechanical Test Failures

The following shall be counted as component failures:

- Components which fail during tests for which the pass/fail criteria are inherent in the test method, e.g. solderability, robustness of terminations, etc.

8.3.2 Electrical Failures

The following shall be counted as component failures:-

- (a) Components which, when subjected to electrical measurements on completion of environmental tests, in accordance with either Table 2 or Table 6, as specified in the Detail Specification, fail one or more of the applicable limits.
- (b) Components which, when subjected to electrical measurements at intermediate and end-points during endurance testing, in accordance with Table 6 of the Detail Specification, fail one or more of the applicable limits.
- (c) Components which, when subjected to measurement of electrical characteristics, in accordance with Tables 2 and 3 of the Detail Specification, fail one or more of the applicable limits.

8.3.3 Other Failures

The following additional failures may also occur during qualification testing or lot acceptance testing:-

- (a) Components failing to comply with the requirements of ESA/SCC Basic Specification No. 20500.
- (b) Lost components.

8.4 FAILED COMPONENTS

A component shall be considered as failed if it exhibits one or more of the failure modes detailed in Para. 8.3 of this specification. The allowable number of failed components per subgroup, the aggregate failure constraints and the permitted distribution of such failures are shown at the foot of Charts IV and V of this specification.

When requested by the Qualifying Space Agency or the Orderer, failure analysis of failed components shall be performed by the Manufacturer and the results provided.

Failed components from successful lots shall be marked as such and be stored at the Manufacturer's plant for 24 months.

8.5 LOT FAILURE

A lot shall be considered as failed if the allowable number of failures according to Chart IV or V of this specification, as relevant, has been exceeded.

In the case of lot failure, the Manufacturer shall act in accordance with Para. 4.3.1 of this specification.

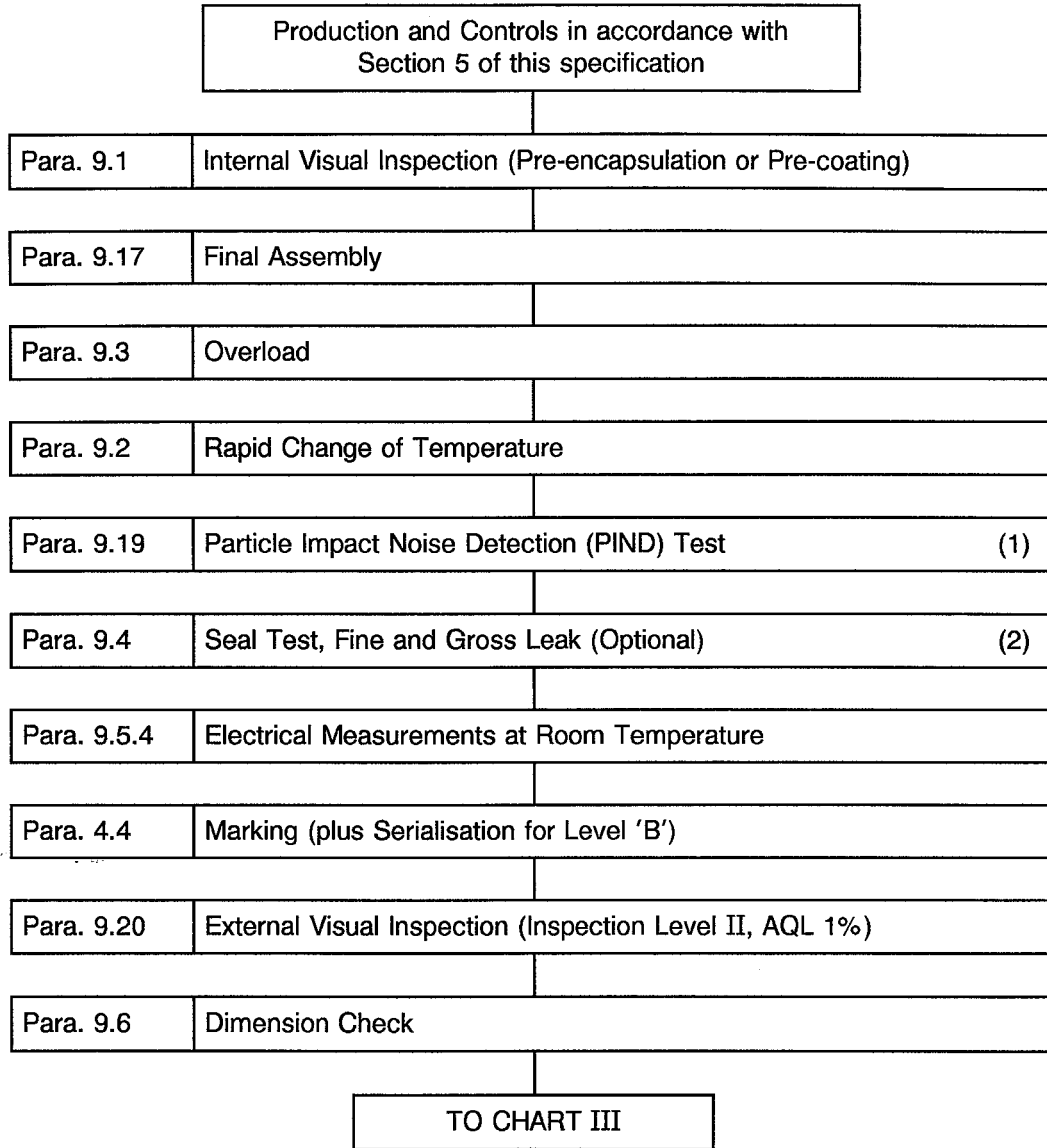
8.6 DOCUMENTATION

For qualification testing, the qualification test data shall be documented in accordance with the requirements of Para. 10.8 of this specification.

In the case of lot acceptance testing, the data shall be documented in accordance with the requirements of Para. 10.9 of this specification.



CHART II - FINAL PRODUCTION TESTS

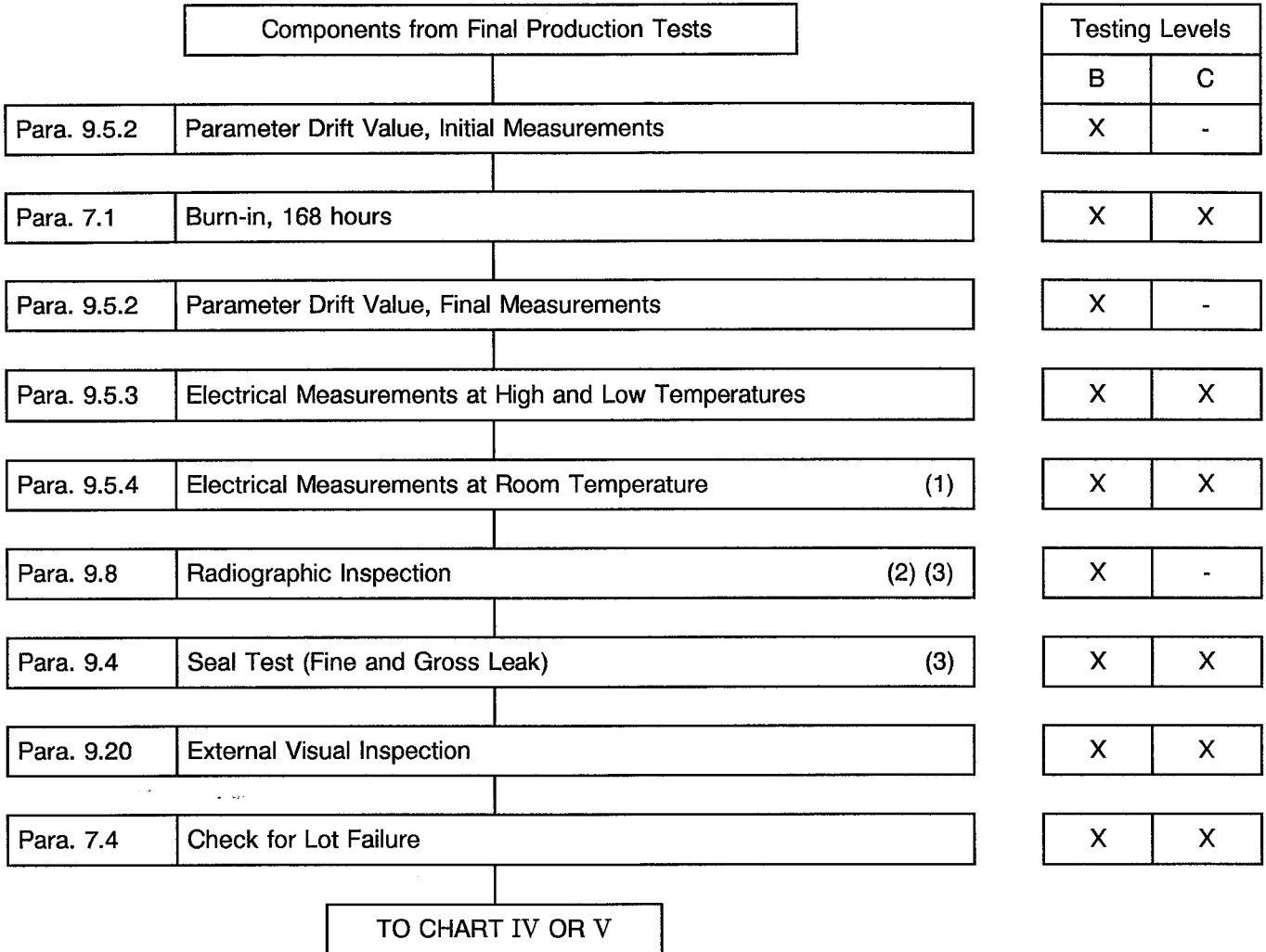


NOTES

1. For cavity devices of Testing Level 'B'.
2. The performance of these tests is left to the Manufacturer's discretion.



CHART III - BURN-IN AND ELECTRICAL MEASUREMENTS

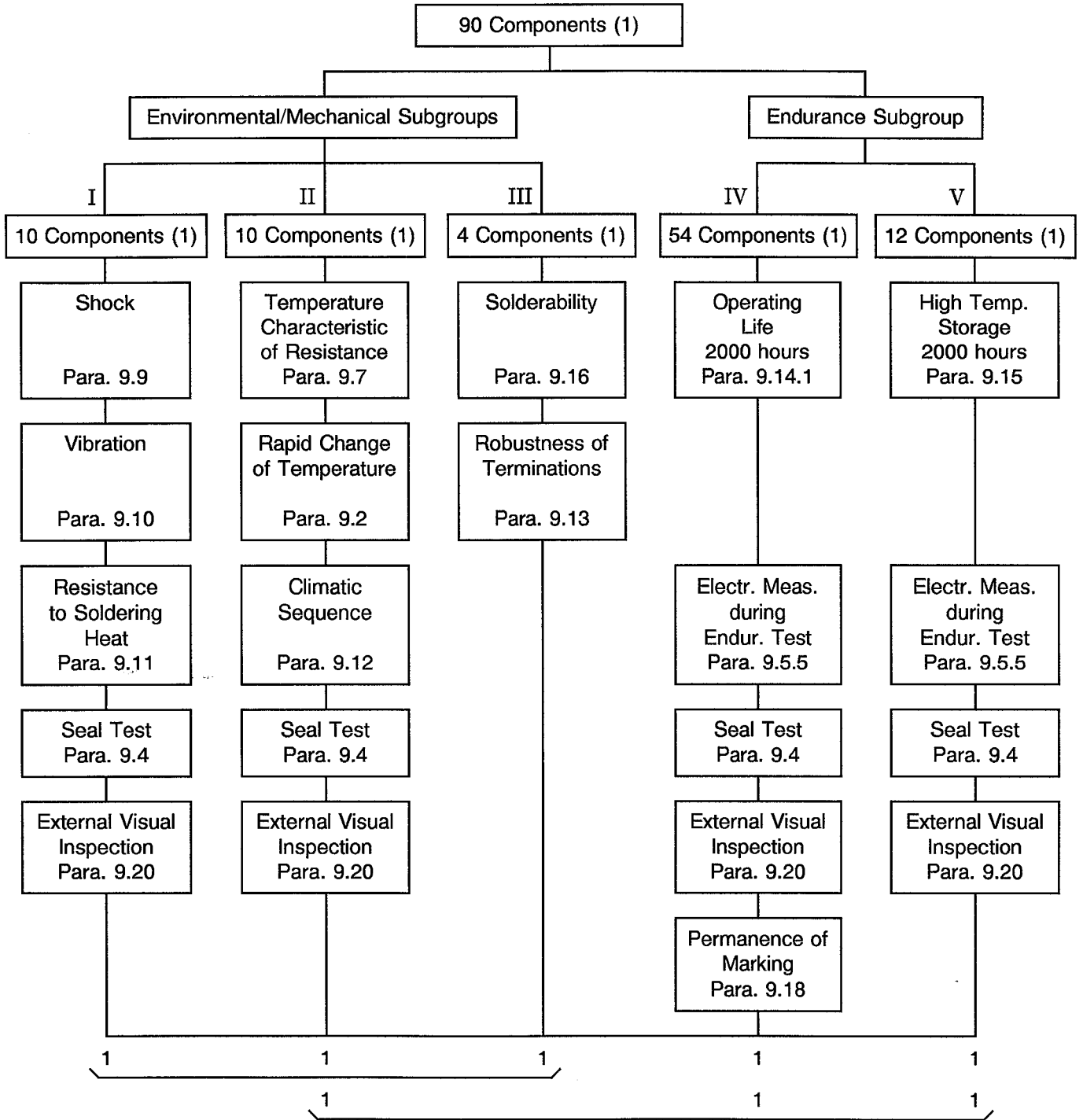


NOTES

1. The measurements of parameters for the purpose of Drift Value Measurements need not be repeated for Electrical Measurements at Room Temperature.
2. Radiographic Inspection may be performed at any point during the test sequence shown in this chart.
3. Radiographic Inspection and Seal Test rejects not to be counted for Lot Failure.



CHART IV - QUALIFICATION TESTS



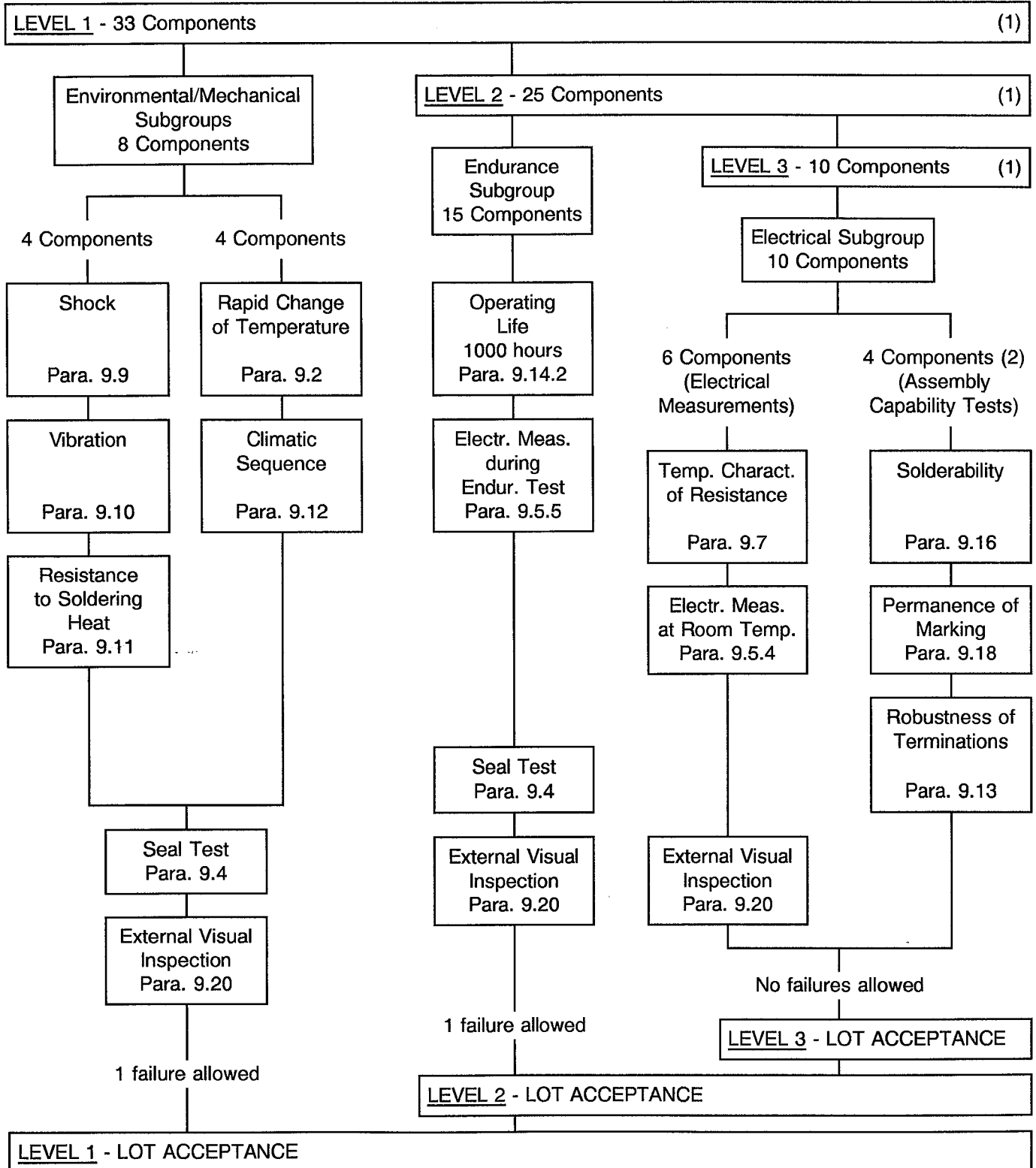
Total allowable number of failed components = 3.

NOTES

1. For distribution within the subgroups, see Para. 8.1.2.



CHART V - LOT ACCEPTANCE TESTS



NOTES

1. For distribution within the subgroups, see Para. 8.2.2.
2. Post burn-in electrical rejects may be used for this test.



9. TEST METHODS AND PROCEDURES

If a Manufacturer elects to eliminate or modify a test method or procedure, the Manufacturer is still responsible for delivering components that meet all of the performance, quality and reliability requirements defined in this specification and the Detail Specification.

Documentation supporting the change shall be approved by the Qualifying Space Agency and retained by the Manufacturer. It shall be copied, when requested, to the Qualifying Space Agency.

The change shall be specified in the Detail Specification and in the P.I.D.

9.1 INTERNAL VISUAL INSPECTION

In accordance with ESA/SCC Basic Specification No. 20400.

9.2 RAPID CHANGE OF TEMPERATURE

9.2.1 Rapid Change of Temperature during Final Production Test

9.2.1.1 Procedure and Recovery

The resistor networks shall be submitted to Test 'Na' of IEC Publication No. 68-2-14 for 5 cycles. The duration of exposure at each of the storage temperature extremes given in Table 1(b) of the Detail Specification shall be 30 minutes.

The resistor networks shall then remain under standard atmospheric conditions for recovery for not less than 1 hour, nor more than 2 hours. After recovery, the resistor networks shall be visually examined. There shall be no evidence of damage.

9.2.1.2 Final Measurement

The resistance shall be measured and shall not exceed the limit prescribed in Table 2 of the Detail Specification.

9.2.2 Rapid Change of Temperature during Qualification and Lot Acceptance Testing

9.2.2.1 Initial Measurement

The resistance shall be measured as specified in Para. 9.5.1.1.

9.2.2.2 Procedure and Recovery

As per Para. 9.2.1.1, but the resistor networks shall be submitted to Test 'Na' of IEC Publication No. 68-2-14 for 25 cycles.

9.2.2.3 Final Measurement

The resistance shall be measured. The change in resistance compared to the value measured according to Para. 9.2.2.1 shall not exceed the limit prescribed in Table 6 of the Detail Specification.

9.3 OVERLOAD

9.3.1 Mounting

The resistor networks shall be mounted on a printed circuit board in such a way that their temperature does not affect the adjoining networks. The resistor networks shall be mounted in still air with no circulation other than that caused by the heat of the resistor networks being operated. The ambient temperature shall be between +19 and +25 °C.



9.3.2 Procedure

The resistor networks shall be operated at twice the rated power dissipation specified in Table 1(b) of the Detail Specification. The duration shall be 5 minutes (+30 – 0 seconds).

9.3.3 Recovery and Final Measurement

After a recovery period of not less than 1 hour, nor more than 2 hours, the resistor networks shall be visually examined. There shall be no evidence of damage and the marking shall be legible. The resistance shall then be measured as specified in Para. 9.5.1.1 and the value shall not exceed the limits specified in Table 2 of the Detail Specification.

9.4 SEAL TEST

9.4.1 Seal Test, Fine Leak

The resistor networks shall be submitted to Test 'Qk', Method 1, of IEC Publication No. 68-2-17. The preferred tracer gas is helium and the permissible leakage rate is not greater than 10^{-8} mbar.dm³/s air equivalent.

9.4.2 Seal Test, Gross Leak

The resistor networks shall be submitted to Test 'Qc', Method 3, of IEC Publication No. 68-2-17. There shall be no evidence of repetitive bubbling.

9.5 ELECTRICAL MEASUREMENTS

9.5.1 General

Electrical measurements and methods shall be as follows:-

9.5.1.1 Resistance

The measurement of resistance shall be made in accordance with Para. 4.5.1 of IEC Publication No. 115-1. The resistance limits at $+22 \pm 3^{\circ}\text{C}$ are given in Table 2 of the Detail Specification.

Each element of the resistor network shall be individually measured.

9.5.1.2 Voltage Proof

The voltage proof shall be tested in accordance with Para. 4.7 of IEC Publication No. 115-1. The following details shall apply:-

(a) **Mounting**

1. Dual-In-Line Packages

The resistor network shall be mounted by clamping its top to a metal plate of sufficient size to extend beyond the resistor network extremities. An additional metal plate shall be mounted against the bottom of the resistor network, avoiding any contact between the plate and the terminals.

2. Single-In-Line and Flat Packages

The resistor network shall be mounted by clamping its sides on metal plates of sufficient size to extend beyond the resistor network extremities.

**(b) Measurement**

During the test, the leakage current shall be monitored.

(c) Visual Examination after Test

On completion of the test, the resistor network shall be visually examined for evidence of damage, arcing or breakdown.

9.5.1.3 Insulation Resistance

This test only applies to insulated resistors.

The insulation resistance shall be tested in accordance with Para. 4.6 of IEC Publication No. 115-1. The mounting conditions described in Para. 9.5.1.2 shall apply.

9.5.2 Parameter Drift Value Measurements

At each of the relevant data points for components of Testing Level 'B', measurements shall be made of all parameters listed in Table 4 of the Detail Specification. All values obtained shall be recorded against serial numbers and the parameter drift calculated.

9.5.3 Electrical Measurements at High and Low Temperatures

For components of Testing Levels 'B' and 'C', the Electrical Measurements at High and Low Temperatures shall be made in accordance with Table 3 of the Detail Specification. Where sample testing is applied, note the requirements of Para. 8.2.3(b). For Testing Level 'B', all values obtained shall be recorded against serial numbers.

9.5.4 Electrical Measurements at Room Temperature

For components of Testing Levels 'B' and 'C', the Measurements of Electrical Characteristics shall be made in accordance with Table 2 of the Detail Specification. Where sample testing is applied, note the requirements of Para. 8.2.3(b). For Testing Level 'B', all values obtained shall be recorded against serial numbers, except during Final Production Tests (Chart II).

9.5.5 Electrical Measurements during Endurance Testing

At each of the relevant data points specified for Endurance Testing, measurements shall be made of all parameters listed in Table 6 of the Detail Specification. All values obtained shall be recorded against serial numbers and the Parameter Drift calculated, if required.

9.6 DIMENSION CHECK

In accordance with ESA/SCC Basic Specification No. 20500 and the Detail Specification. To be performed on 5 samples only.

If 1 failure occurs, the complete lot shall be checked.

9.7 TEMPERATURE CHARACTERISTIC OF RESISTANCE (TEMPERATURE COEFFICIENT)

The resistors shall be dried as prescribed in the Detail Specification by applying either Procedure I or II as follows:-

9.7.1 Procedure I

For 24 ± 4 hours in an oven at a temperature of $+55 \pm 2$ °C and with a relative humidity not exceeding 20%.



9.7.2 Procedure II

For 96 ± 4 hours in an oven at a temperature of $+100 \pm 5$ °C. The resistors shall then be allowed to cool in a desiccator, using a suitable desiccant such as activated alumina or silica gel, and be kept therein from the time of removal from the oven until the beginning of the test.

9.7.3 Test Procedure

The resistors shall be maintained at each of the following temperatures in turn:-

- (a) $+22 \pm 3$ °C.
- (b) Lower category ± 3 °C.
- (c) $+22 \pm 3$ °C.
- (d) Upper category ± 3 °C.
- (e) $+22 \pm 3$ °C.

10 to 15 minutes after the resistors have reached thermal stability, resistance measurements shall be made at each of the above mentioned temperatures, using the method specified in Para. 9.5.1.1. The temperature of the resistors at the time of measurement shall be recorded. The error of temperature measurement shall not exceed 1°C.

Thermal stability will have been reached when no further change in resistance is observed between 2 successive measurements taken at 15-minute intervals.

The temperature characteristic of resistance between +22°C and each of the other specified temperatures shall be calculated from the following formula:

Temperature characteristic of resistance (temperature coefficient) =
 (in Percent/°C) $100 \frac{\Delta R}{R \Delta T} \times K$ or (in $10^{-6}/^{\circ}\text{C}$) $10^6 \frac{\Delta R}{R \Delta T} \times K$, where

'K' = $\frac{\text{difference between nominal specified temperatures}}{\text{difference between recorded temperatures}}$

'ΔT' = difference between recorded temperatures and where, if the resistances recorded above are designated Ra, Rb, Rc, Rd and Re, 'R' and 'ΔR' are given as shown in the table below.

	LOWER CATEGORY TEMPERATURE	UPPER CATEGORY TEMPERATURE
R	$1/2 (R_a + R_c)$	$1/2 (R_c + R_e)$
ΔR	$R_b - R$	$R_d - R$

The temperature characteristic of resistance, determined as described above, shall not exceed the value prescribed in the Detail Specification for the appropriate category temperature. Where the resistance value is greater than 5.0Ω but less than 10Ω, the temperature characteristic of resistance shall not exceed twice the value prescribed in the Detail Specification.

N.B.

The temperature characteristic of resistance is not specified for resistance values of less than 5.0Ω due to difficulty of accurate measurement.

**9.8 RADIOGRAPHIC INSPECTION**

In accordance with ESA/SCC Basic Specification No. 20900.

9.9 SHOCK

The resistor networks shall be tested in accordance with Para. 4.21 of IEC Publication No. 115-1 and Test 'Ea' of IEC Publication No. 68-2-27. The following details shall apply:-

(a) Mounting Method

The resistor networks shall be mounted on a suitable test board of glass base of 1.5mm thickness. The test board shall be such that it shall not be the cause of, nor contribute to, any failure of a resistor network in any of the tests in which it may be used.

Resistor networks must be spaced at least 12mm from each other. The mounting fixture shall be constructed in such a manner as to ensure that the mounting supports remain in a static condition with reference to the shock test table.

Resistor networks shall be mounted in relation to the test equipment in such a manner that the most detrimental stress is applied. The test leads used during this test shall be no larger than AWG Size 22 stranded wire, so that the influence of the test lead on the package lead will be held to a minimum. The test lead length shall be no longer than necessary.

(b) Test Conditions

Sawtooth pulse:

- Peak Value: 100g.
- Duration: 6.0ms.

(c) Measurements before Shock

Resistance shall be measured as specified in Para. 9.5.1.1.

(d) Measurements during Shock

Not applicable.

(e) Measurements after Shock

Resistance shall be measured as specified in Para. 9.5.1.1. The change in resistance with regard to the initial measurement shall not exceed the limits specified in Table 6 of the Detail Specification.

(f) Visual Examination after Test

The resistor networks shall be visually examined. There shall be no evidence of damage.

9.10 VIBRATION

The resistor networks shall be tested in accordance with Para. 4.22 of IEC Publication No. 115-1 and Test 'Fc' of IEC Publication No. 68-2-6. The following details shall apply:-

(a) Mounting Method

As Para. 9.9(a).

(b) Test Conditions

- Amplitude: 20g.
- Frequency Range: 10 - 2 000 Hz.
- Duration: 12 cycles (20 minutes) in each of the 3 mutually perpendicular directions.

**(c) Measurements before Vibration**

As Para. 9.9(c).

(d) Measurements during Vibration

As Para. 9.9(d).

(e) Measurements after Vibration

As Para. 9.9(e).

9.11 RESISTANCE TO SOLDERING HEAT

The resistor networks shall be tested in accordance with Para. 4.18 of IEC Publication No. 115-1 and Test 'Tb' of IEC Publication No. 68-2-20. The following details shall apply:-

(a) Special Preparation of Specimens

Sample units shall not have been soldered in any previous tests.

The resistance shall be measured as specified in Para. 9.5.1.1.

(b) Test Condition

Method 1A.

Duration: 10 ± 1 seconds.

(c) Application of Flux

When flux is used, the terminations to be tested shall be immersed in the flux, which is at room ambient temperature, to the depth specified for the solder dip. The duration of the immersion shall be from 5 to 10 seconds.

(d) Cooling Time prior to Measurement and Visual Examination

10 ± 1 seconds.

(e) Measurement and Visual Examination

The resistance shall be measured as specified in Para. 9.5.1.1.

The change in resistance compared to the value measured initially shall not exceed the limits prescribed in Table 6 of the Detail Specification.

The resistor networks shall be visually examined. There shall be no evidence of damage.

9.12 CLIMATIC SEQUENCE**9.12.1 Initial Measurement**

The resistor networks shall be dried, using either Procedure I or II, specified in Para. 9.7.1 and 9.7.2, as prescribed in the Detail Specification.

The resistance shall then be measured as specified in Para. 9.5.1.1.

9.12.2 Dry Heat

The resistor networks shall be subjected to Test 'Ba' of IEC Publication No. 68-2-2 at the upper category temperature, taking into account the following deviation:-

The resistor networks shall be removed from the chamber and exposed to standard atmospheric conditions for recovery, for not less than 4 hours.

**9.12.3 Damp Heat (Accelerated), First Cycle**

The resistor networks shall be subjected to Test 'Db' of IEC Publication No. 68-2-30, for 1 cycle of 24 hours. After recovery, the resistor networks shall be immediately subjected to the cold test.

9.12.4 Cold Test

The resistor networks shall be subjected to Test 'Aa' of IEC Publication No. 68-2-1 at the lower category temperature. After 1 hour of stabilisation at this temperature, full rated continuous voltage as specified in Table 1(b) of the Detail Specification shall be applied for 45 minutes.

The resistor networks may be loaded individually or in parallel. They shall be removed from the chamber and exposed to standard atmospheric conditions for recovery for not less than 4 hours.

9.12.5 Low Air Pressure

The resistor networks shall be subjected to Test 'M' of IEC Publication No. 68-2-13, using a pressure of 20 ± 1.0 mbar with full rated continuous voltage applied. The test shall be performed at a temperature between +15 and +35 °C. The duration of the test shall be 1 hour.

9.12.6 Damp Heat (Accelerated), Remaining Cycles

The resistor networks shall be subjected to Test 'Db' of IEC Publication No. 68-2-30 for 5 cycles of 24 hours.

9.12.7 D.C. Load

At the end of the conditioning period, the resistor networks shall be subjected to the standard atmospheric conditions for recovery. The time of transfer shall be as brief as possible and in no case exceed 5 minutes.

At 30 ± 5 minutes after removal from the chamber for the damp heat cycle test, the resistor networks shall be subjected to a d.c. voltage for 1 minute. The voltage shall be the rated or limiting element voltage, whichever is the smaller.

The resistor networks shall then be subjected to the standard atmospheric conditions for not less than 1 hour and not more than 2 hours.

9.12.8 Measurement and Visual Examination

The resistor networks shall then be visually examined. There shall be no evidence of damage and the marking shall be legible.

The resistance and, for insulated types only, the insulation resistance shall then be measured as specified in Paras. 9.5.1.1 and 9.5.1.3 respectively.

The change in resistance compared to the value measured in Para. 9.12.1 shall not exceed the limits prescribed in Table 6 of the Detail Specification.

The insulation resistance shall be not less than that prescribed in Table 6 of the Detail Specification.

9.13 ROBUSTNESS OF TERMINATIONS**9.13.1 Dual-In-Line and Flat Packages**

The resistor networks shall be subjected to Test 'Ub' of IEC Publication No. 68-2-21. The following details shall apply:-

(a) Initial Measurement

The resistance shall be measured as specified in Para. 9.5.1.1.

**(b) Number of Terminations to be Tested**

Three leads (excluding corner leads) or 10% of the leads (whichever is greater) are to be randomly selected on each component of the sample.

(c) Measurement and Visual Examination

The resistor networks shall be visually examined. There shall be no broken termination.

The resistance shall be measured as specified in Para. 9.5.1.1.

The change in resistance compared to the value measured initially shall not exceed the limits prescribed in Table 6 of the Detail Specification.

9.13.2 Single-In-Line Packages

The resistor networks shall be subjected to Test 'Ua1' of IEC Publication No. 68-2-21. The following details shall apply:-

(a) Initial Measurement

The resistance shall be measured as specified in Para. 9.5.1.1.

(b) Number of Terminations to be Tested

Three leads (excluding end leads) or 10% of the leads (whichever is greater) are to be randomly selected on each component of the sample.

(c) Measurement and Visual Examination

The resistor networks shall be visually examined. There shall be no broken termination.

The resistance shall be measured as specified in Para. 9.5.1.1.

The change in resistance compared to the value measured initially shall not exceed the limits prescribed in Table 6 of the Detail Specification.

9.14 OPERATING LIFE

Operating life shall be performed in accordance with Para. 4.25 of IEC Publication No. 115-1.

9.14.1 Operating Life during Qualification Testing

(a) Duration: 2 000 hours.

(b) Temperature Measurements

Distance of temperature measurements from specimens: No requirement.

(c) Method of Mounting

The resistor networks shall be mounted on a suitable test board of glass base of 1.5mm thickness. The test board shall be such that it shall not be the cause of, nor contribute to, any failure of resistor network in any of the tests in which it may be used. The wiring shall be connected to the landing pads at the top and bottom of the circuit board.

The resistor networks must be spaced at least 12mm from each other. If forced air circulation is employed, the air velocity shall not exceed 150 metres per minute and there shall be no direct impingement of the forced air supply on the resistor networks.

**(d) Operating Conditions**

As specified in the Detail Specification.

The voltage shall be applied simultaneously to each element of the resistor network in cycles of 1.5 hours 'ON' and 0.5 hours 'OFF' throughout the test. The 0.5 hour 'OFF' periods are included in the total test duration.

The voltage shall be regulated and controlled to maintain $\pm 5\%$ of the rated continuous working voltage. In no case shall the resistor network maximum power rating be exceeded.

If the number of resistors in the network exceeds the 'critical' number, the voltage applied shall be reduced such that the power dissipated by each resistor shall be the resistor network power rating divided by the number of resistors in the network.

The 'critical' number is determined by dividing the network power rating by the individual resistor power rating.

(e) Measurements

Measurements may be made inside or outside the chamber:-

1. Measurements Inside the Chamber

When measurements are made inside the chamber, the Initial Measurement shall be made at the applicable test temperature after temperature stabilisation and within 8 hours of the exposure of the resistor networks to the test temperature. This Initial Measurement shall be used as the reference for all subsequent measurements made under the same conditions.

2. Measurements Outside the Chamber

When measurements are made outside the chamber, the Initial Measurement shall be made at room ambient temperature and this temperature shall be noted. This Initial Measurement shall be used as the reference for all subsequent measurements made under the same conditions. Before making data point measurements, the resistor networks shall have been outside the chamber for a minimum period of 45 minutes and shall have stabilised at room ambient temperature.

(f) Data Points

Measurements at Intermediate and End-points in accordance with Table 6 of the Detail Specification at 0, 500 \pm 48, 1 000 \pm 48 and 2 000 \pm 48 hours.

In the case where Table 6 specifies 'changes', the drift shall always be related to the 0-hour measurement.

9.14.2 Operating Life during Lot Acceptance Testing

(a) **Duration:** 1 000 hours.

(b) Temperature Measurements

Distance of temperature measurements from specimens: No requirement.

(c) **Method of Mounting:** See Para. 9.14.1(c).

(d) **Operating Conditions:** See Para. 9.14.1(d).

(e) **Measurements:** See Para. 9.14.1(e).

(f) Data Points

Measurements at Intermediate and End-points in accordance with Table 6 of the Detail Specification at 0, 500 \pm 48 and 1 000 \pm 48 hours.

In the case where Table 6 specifies 'changes', the drift shall always be related to the 0-hour measurement.

**9.15** HIGH TEMPERATURE STORAGE

(a) **Duration:** 2 000 hours.

(b) **Method of Mounting**

Mounting as per Para. 9.14.1(c) is optional. However, the resistor networks shall be isolated from the metal surfaces of ovens.

(c) **Test Conditions**

1. The temperature shall be within $\pm 2^{\circ}\text{C}$ of the maximum storage temperature defined in Table 1(b) of the Detail Specification.
2. Zero dissipation, in a chamber with forced air circulation.

(d) **Data Points**

Measurements at Intermediate and End-points in accordance with Table 6 of the Detail Specification at 0, 500 ± 48 , $1\ 000 \pm 48$ and $2\ 000 \pm 48$ hours.

In the case where Table 6 specifies 'changes', the drift shall always be related to the 0-hour measurement.

9.16 SOLDERABILITY

The resistor networks shall be subjected to Test 'Ta' of IEC Publication No. 68-2-20. The following details shall apply:-

(a) **Special Preparation of Specimens**

Sample units shall not have been soldered in any previous tests.

(b) **Test Condition**

Method 1.

Duration: 5.0 ± 0.5 seconds.

Immersion Depth: To 1.5mm of the body of the resistor network.

(c) **Application of Flux**

When flux is used, the terminations to be tested shall be immersed in the flux, which is at room ambient temperature, to the depth specified for the solder dip. The duration of the immersion shall be from 5 to 10 seconds.

(d) **Visual Examination**

The resistor networks shall be visually examined. The dipped portion of the terminations shall be at least 95% covered by a continuous new solder coating.

9.17 FINAL ASSEMBLY

Final Assembly shall be performed in accordance with the Process Identification Document (P.I.D.).

9.18 PERMANENCE OF MARKING

In accordance with ESA/SCC Basic Specification No. 24800.

9.19 PARTICLE IMPACT NOISE DETECTION (PIND)

In accordance with Method 2020 of MIL-STD-883, Condition 'A' or 'B'.

9.20 EXTERNAL VISUAL INSPECTION

In accordance with ESA/SCC Basic Specification No. 20500.

**10. DATA DOCUMENTATION****10.1 GENERAL**

For the qualification approval records and with each component delivery, a data documentation package is required. Depending on the testing level and lot acceptance level specified for the component, this package shall be compiled from:-

- (a) Cover sheet (or sheets).
- (b) List of equipment (testing and measuring).
- (c) List of test references.
- (d) Special in-process control test data (when required by the Detail Specification).
- (e) Final production test data (Chart II) (but see Para. 10.6).
- (f) Burn-in and electrical measurement data (Chart III).
- (g) Qualification test data (Chart IV).
- (h) Lot acceptance test data (Chart V) (when applicable).
- (i) Failed component list (see Paras. 7.3 and 8.4) and failure analysis report (see Para. 8.4).
- (j) Certificate of Conformity.
- (k) Radiographic inspection photographs.

Items (a) to (k) inclusive shall be grouped, preferably as subpackages and, for identification purposes, each page shall include the following information:

- ESA/SCC Component number.
- Manufacturer's name.
- Lot identification.
- Date of establishment of the document.
- Page number.

10.1.1 Qualification Approval

In the case of qualification approval, the items listed in Para. 10.1 (a) to (k) less item (h) are required.

10.1.2 Testing Level 'B'**10.1.2.1 Qualified Components**

For deliveries of qualified components, the following documentation shall be supplied:-

- (a) Cover sheet (if all of the information is not included on the Certificate of Conformity).
- (b) Certificate of Conformity (including range of delivered serial numbers).
- (c) Attributes record of measurements, tests and inspections performed in Chart II, Chart III (including PDA figure) and Chart V (where applicable).
- (d) Failed components list.



10.1.2.2 Unqualified Components

For deliveries of unqualified components, the documentation to be supplied shall be in accordance with Para. 10.1.2.1 plus the following:-

- (a) Read and record data from Chart III.
- (b) Special in-process control data (where applicable).
- (c) Failure analysis report on failed components.

10.1.3 Testing Level "C"

10.1.3.1 Qualified Components

For deliveries of qualified components, the following documentation shall be supplied:-

- (a) Certificate of Conformity.

10.1.3.2 Unqualified Components

For deliveries of unqualified components, the documentation to be supplied shall be in accordance with Para. 10.1.3.1 plus the following:-

- (a) Cover sheet (if all of the information is not included on the Certificate of Conformity).
- (b) Attributes record of all measurements, tests and inspections performed in Charts II, III and V (when applicable).
- (c) Failed components list (including Failure Analysis Report).
- (d) Special in-process control data (when applicable).

10.1.4 Data Retention/Data Access

If not delivered, all data shall be retained by the Manufacturer for a minimum of 5 years during which time it shall be available to the Qualifying Space Agency and the Orderer, if requested, for review. The Manufacturer shall deliver variables Data/Reports to the Orderer if required by the Purchase Order.

10.2 COVER SHEET(S)

The cover sheet(s) of the data documentation package shall include as a minimum:-

- (a) Reference to the Detail Specification, including issue and date.
- (b) Reference to the applicable ESA/SCC Generic Specification, including issue and date.
- (c) Component type and number.
- (d) Lot identification.
- (e) Range of delivered serial numbers (for components of testing level 'B').
- (f) Number of purchase order.
- (g) Information relative to any additions to this specification and/or the Detail Specification.
- (h) Manufacturer's name and address.
- (j) Location of the manufacturing plant.
- (k) Signature on behalf of Manufacturer.
- (l) Total number of pages of the data package.

**10.3 LIST OF EQUIPMENT USED**

A list of equipment used for tests and measurements shall be prepared, if not in accordance with the data given in the Process Identification Document (P.I.D.). Where applicable, this list shall contain inventory number, Manufacturer's type number, serial number, etc. This list shall indicate for which tests such equipment was used.

10.4 LIST OF TEST REFERENCES

This list shall include all Manufacturer's references or codes which are necessary to correlate the test data provided with the applicable tests specified in the tables of the Detail Specification.

10.5 SPECIAL IN-PROCESS CONTROL DATA

As specified in the Detail Specification.

10.6 FINAL PRODUCTION TEST DATA (CHART II)

A test result summary shall be compiled showing the total number of components submitted to, and the total number rejected after, each of the following tests:

- Internal visual inspection (Para. 9.1).
- Overload (Para. 9.3).
- Rapid change of temperature (Para. 9.2).
- PIND test (Para. 9.19) (when applicable).
- Seal test (Para. 9.4).
- Electrical measurements at room temperature (Para. 9.5.4).
- External visual inspection (Para. 9.20).
- Dimension check (Para. 9.6).

The final production test data shall form an integral part of the data documentation package, but it is not a mandatory requirement that it be delivered with the qualification lot or delivery lot. However, the data package to be delivered shall contain the information as detailed in Paras. 10.1.2 and 10.1.3 or at least shall contain a list of final production tests actually performed and a certification that the data is available for review.

10.7 BURN-IN AND ELECTRICAL MEASUREMENT DATA (CHART III)**10.7.1 Testing Level 'B'**

For components of testing level 'B', all data shall refer to the relevant serial numbers. Against these serial numbers, data shall be recorded of the following:-

- (a) 0-hour measurement for burn-in.
- (b) 168-hour measurement for burn-in.
- (c) Delta values after burn-in.
- (d) Values obtained during measurements at high and low temperatures (Table 3 of the Detail Specification).
- (e) Values obtained during measurements of electrical characteristics (Table 2 of the Detail Specification).
- (f) Failures during external visual inspection.
- (g) Photographs from radiographic inspection, including those of reject components.



10.7.2 Testing Level 'C'

For components of testing level 'C', a test result summary (i.e. the total number of components subjected to, and the total number rejected from, each of the tests and inspections) shall be prepared.

10.8 QUALIFICATION TEST DATA (CHART IV)

All data shall be referenced to the relevant serial numbers. Detailed records shall be provided of the components submitted to each test in each of the subgroups and of those rejected.

Detailed data shall be provided of all electrical measurements made in accordance with Tables 3 and 6 of the Detail Specification, as and where applicable.

10.9 LOT ACCEPTANCE TEST DATA (CHART V)

10.9.1 Testing Level 'B'

All data shall be referenced to the relevant serial numbers. Detailed records shall be provided of the components submitted to each test in each of the subgroups (as relevant to the lot acceptance level) and of those rejected.

Detailed data shall be provided of all electrical measurements made in accordance with Tables 2, 3 and 6 of the Detail Specification, as and where applicable.

10.9.2 Testing Level 'C'

A test result summary (i.e. the total number of components submitted to, and the total number rejected from, each of the tests and inspections) as relevant to the lot acceptance level, shall be provided.

In the case of lot acceptance 2 testing, all data in respect of electrical measurements made in accordance with Table 6 of the Detail Specification shall be referenced to the relevant serial numbers (see Para. 8.2.4(a)).

In the case of lot acceptance 1 testing, all data in respect of electrical measurements made in accordance with Tables 2 and 6 of the Detail Specification shall be referenced to the relevant serial numbers (see Para. 8.2.5(a)).

10.10 FAILED COMPONENTS LIST AND FAILURE ANALYSIS REPORT

The failed component list and failure analysis report shall provide full details of:-

- (a) The reference number and description of the test or measurement performed as defined in this specification and/or the Detail Specification.
- (b) The serial number (if applicable) of the failed component.
- (c) The failed parameter and the failure mode of the component.
- (d) Detailed failure analysis, if requested.

10.11 CERTIFICATE OF CONFORMITY

A Certificate of Conformity shall be established as defined in ESA/SCC Basic Specification No. 20100.



11. DELIVERY

For qualification approval, the disposition of the qualification test lot and its related documentation shall be as specified in ESA/SCC Basic Specification No. 20100 and the relevant paragraphs of Section 10 of this specification.

For procurement, for each order, the items forming the delivery are:-

- (a) The delivery lot.
- (b) The components used for lot acceptance testing (when applicable), but not forming part of the delivery lot (see Para's 8.2.3(d), 8.2.4(b) and 8.2.5(b)).
- (c) The relevant documentation in accordance with the requirements of Section 10 of this specification.

In the case of a component for which a valid qualification approval is in force, all data of all components submitted to LA1 and LA2 testing shall also be copied, when requested, to the relevant Qualifying Space Agency.

12. PACKAGING AND DESPATCH

The packaging and despatch of components to this specification shall be in accordance with the requirements of ESA/SCC Basic Specification No. 20600.



ANNEXE I

LTPD SAMPLING PLAN LOT SIZES GREATER THAN 200 DEVICES

Minimum size of sample to be tested to assure with a 90% confidence that a lot whose Percent Defective equals the specified LTPD is not accepted (single sample).

Max. Percent Defective (LTPD) or λ	50	30	20	15	10	7	5	3	2	1.5	1	0.7	0.5	0.3	0.2	0.15	0.1
Acceptance Number (c) ($r = c + 1$)	MINIMUM SAMPLE SIZES (FOR DEVICE-HOURS REQUIRED FOR LIFE TEST, MULTIPLY BY 1000)																
0	5 (1.03)	8 (0.64)	11 (0.46)	15 (0.34)	22 (0.23)	32 (0.16)	45 (0.11)	76 (0.07)	116 (0.04)	153 (0.03)	231 (0.02)	328 (0.02)	461 (0.01)	767 (0.007)	1152 (0.005)	1534 (0.003)	2303 (0.002)
1	8 (4.4)	13 (2.7)	18 (2.0)	25 (1.4)	38 (0.94)	55 (0.65)	77 (0.46)	129 (0.28)	195 (0.18)	258 (0.14)	390 (0.09)	555 (0.06)	778 (0.045)	1296 (0.027)	1946 (0.018)	2592 (0.013)	3891 (0.009)
2	11 (7.4)	18 (4.5)	25 (3.4)	34 (2.24)	52 (1.6)	75 (1.1)	105 (0.78)	176 (0.47)	266 (0.31)	354 (0.23)	533 (0.15)	759 (0.11)	1065 (0.080)	1773 (0.045)	2662 (0.031)	3547 (0.022)	5323 (0.015)
3	13 (10.5)	22 (6.2)	32 (4.4)	43 (3.2)	65 (2.1)	94 (1.5)	132 (1.0)	221 (0.62)	333 (0.41)	444 (0.31)	668 (0.20)	953 (0.14)	1337 (0.10)	2226 (0.062)	3341 (0.041)	4452 (0.031)	6681 (0.018)
4	16 (12.3)	27 (7.3)	38 (5.3)	52 (3.9)	78 (2.6)	113 (1.8)	158 (1.3)	265 (0.75)	398 (0.50)	531 (0.37)	798 (0.25)	1140 (0.17)	1599 (0.12)	2663 (0.074)	3997 (0.049)	5327 (0.037)	7994 (0.025)
5	19 (13.8)	31 (8.4)	45 (6.0)	60 (4.4)	91 (2.9)	131 (2.0)	184 (1.4)	308 (0.85)	462 (0.57)	617 (0.42)	927 (0.28)	1323 (0.20)	1855 (0.14)	3090 (0.085)	4638 (0.056)	6181 (0.042)	9275 (0.028)
6	21 (15.6)	35 (9.4)	51 (6.6)	68 (4.9)	104 (3.2)	149 (2.2)	209 (1.6)	349 (0.94)	528 (0.62)	700 (0.47)	1054 (0.31)	1503 (0.22)	2107 (0.155)	3509 (0.093)	5267 (0.062)	7019 (0.047)	10533 (0.031)
7	24 (16.6)	39 (10.2)	57 (7.2)	77 (5.3)	116 (3.5)	166 (2.4)	234 (1.7)	390 (1.0)	589 (0.67)	783 (0.51)	1178 (0.34)	1680 (0.24)	2355 (0.17)	3922 (0.101)	5886 (0.067)	7845 (0.051)	11771 (0.034)
8	26 (18.1)	43 (10.9)	63 (7.7)	85 (5.6)	128 (3.7)	184 (2.6)	258 (1.8)	431 (1.1)	648 (0.72)	864 (0.54)	1300 (0.36)	1854 (0.25)	2599 (0.18)	4329 (0.108)	6498 (0.072)	8660 (0.054)	12995 (0.036)
9	28 (19.4)	47 (11.5)	69 (8.1)	93 (6.0)	140 (3.9)	201 (2.7)	282 (1.9)	471 (1.2)	709 (0.77)	945 (0.58)	1421 (0.38)	2027 (0.27)	2842 (0.19)	4733 (0.114)	7103 (0.077)	9468 (0.057)	14206 (0.038)
10	31 (19.9)	51 (12.1)	75 (8.4)	100 (6.3)	152 (4.1)	218 (2.9)	306 (2.0)	511 (1.2)	770 (0.80)	1025 (0.60)	1541 (0.40)	2199 (0.28)	3082 (0.20)	5133 (0.120)	7704 (0.080)	10268 (0.060)	15407 (0.040)
11	33 (21.0)	54 (12.8)	83 (8.3)	111 (6.2)	166 (4.2)	238 (2.9)	332 (2.1)	555 (1.2)	832 (0.83)	1109 (0.62)	1664 (0.42)	2378 (0.29)	3323 (0.21)	5546 (0.12)	8319 (0.083)	11092 (0.062)	16638 (0.042)
12	36 (21.4)	59 (13.0)	89 (8.6)	119 (6.5)	178 (4.3)	254 (3.0)	356 (2.2)	594 (1.3)	890 (0.86)	1187 (0.65)	1781 (0.43)	2544 (0.3)	3562 (0.22)	5936 (0.13)	8904 (0.086)	11872 (0.065)	17808 (0.043)
13	38 (22.3)	63 (13.4)	95 (8.9)	126 (6.7)	190 (4.5)	271 (3.1)	379 (2.26)	632 (1.3)	948 (0.89)	1264 (0.67)	1896 (0.44)	2709 (0.31)	3793 (0.22)	6321 (0.134)	9482 (0.089)	12643 (0.067)	18964 (0.045)
14	40 (23.1)	67 (13.8)	101 (9.2)	134 (6.9)	201 (4.6)	288 (3.2)	403 (2.3)	672 (1.4)	1007 (0.92)	1343 (0.69)	2015 (0.46)	2878 (0.32)	4029 (0.23)	6716 (0.138)	10073 (0.092)	13431 (0.069)	20146 (0.046)
15	43 (23.3)	71 (14.1)	107 (9.4)	142 (7.1)	213 (4.7)	305 (3.3)	426 (2.36)	711 (1.41)	1066 (0.94)	1422 (0.71)	2133 (0.47)	3046 (0.33)	4265 (0.235)	7108 (0.141)	10662 (0.094)	14216 (0.070)	21324 (0.047)
16	45 (24.1)	74 (14.0)	112 (9.7)	150 (7.2)	225 (4.8)	321 (3.37)	450 (2.41)	750 (1.44)	1124 (0.96)	1499 (0.72)	2249 (0.48)	3212 (0.337)	4497 (0.241)	7496 (0.144)	11244 (0.096)	14992 (0.072)	22487 (0.048)
17	47 (24.7)	79 (14.7)	118 (9.86)	158 (7.36)	236 (4.93)	338 (3.44)	473 (2.46)	788 (1.48)	1182 (0.98)	1576 (0.74)	2364 (0.49)	3377 (0.344)	4728 (0.246)	7880 (0.148)	11819 (0.098)	15759 (0.074)	23639 (0.049)
18	50 (24.9)	83 (15.0)	124 (10.0)	165 (7.54)	248 (5.02)	354 (3.51)	496 (2.51)	826 (1.51)	1239 (1.0)	1652 (0.75)	2478 (0.50)	3540 (0.351)	4956 (0.251)	8260 (0.151)	12390 (0.100)	16520 (0.075)	24780 (0.050)
19	52 (25.5)	86 (15.4)	130 (10.2)	173 (7.76)	259 (5.12)	370 (3.58)	518 (2.56)	864 (1.53)	1296 (1.02)	1728 (0.77)	2591 (0.52)	3702 (0.358)	5183 (0.256)	8638 (0.153)	12957 (0.102)	17276 (0.077)	25914 (0.051)
20	54 (26.1)	90 (15.6)	135 (10.4)	180 (7.82)	271 (5.19)	386 (3.65)	541 (2.60)	902 (1.56)	1353 (1.04)	1803 (0.78)	2705 (0.52)	3864 (0.364)	5410 (0.260)	9017 (0.156)	13526 (0.104)	18034 (0.078)	27051 (0.052)
26	65 (27.0)	109 (16.1)	163 (10.8)	217 (8.08)	326 (5.38)	466 (3.76)	652 (2.69)	1086 (1.61)	1629 (1.08)	2173 (0.807)	3259 (0.538)	4656 (0.376)	6518 (0.269)	10863 (0.161)	16295 (0.108)	21726 (0.081)	32589 (0.054)

- (1) Sample sizes are based upon the Poisson exponential binomial limit.
- (2) The minimum quality (approximate AQL) required to accept (on the average) 19 of 20 lots is shown in parentheses for information only.



ANNEXE I

LTPD SAMPLING PLAN LOT SIZES LESS THAN, OR EQUAL TO, 200 DEVICES

C=0												
N	10	20	30	40	50	60	80	100	120	150	160	200
n	AQL LTPD	AQL LTPD	AQL LTPD	AQL LTPD	AQL LTPD	AQL LTPD	AQL LTPD	AQL LTPD	AQL LTPD	AQL LTPD	AQL LTPD	AQL LTPD
2	2.2 65	2.5 66	2.5 67	2.5 67	2.5 67	2.5 68	2.5 68	2.5 68	2.5 68	2.5 68	2.5 68	2.5 68
4	1.2 36	1.2 40	1.2 42	1.2 42	1.3 42	1.3 43	1.3 43	1.3 43	1.3 43	1.3 43	1.3 44	1.3 44
5	1.0 29	1.0 33	1.0 34	1.0 35	1.0 35	1.0 35	1.0 36	1.0 36	1.0 37	1.0 37	1.0 37	1.0 37
8	0.5 15	0.6 20	0.6 22	0.6 23	0.6 23	0.6 23	0.6 24	0.7 24	0.7 24	0.7 24	0.7 24	0.7 25
10		0.4 15	0.5 17	0.5 19	0.5 19	0.5 19	0.5 20	0.5 20	0.5 20	0.5 20	0.5 20	0.5 20
16		0.2 6.9	0.25 10	0.25 11	0.3 11	0.3 12	0.3 12	0.3 13	0.3 13	0.3 13	0.3 13	0.3 13
20			0.2 6.8	0.2 8.0	0.25 8.7	0.25 9.0	0.25 9.4	0.25 10	0.25 10	0.25 10	0.25 10	0.25 11
25			0.15 4.3	0.15 5.7	0.2 6.4	0.2 6.9	0.2 7.4	0.2 7.5	0.2 7.6	0.2 7.7	0.2 7.8	0.2 7.9
32				0.1 3.7	0.1 4.4	0.1 5.0	0.1 5.5	0.1 5.9	0.15 6.0	0.15 6.2	0.15 6.3	0.15 6.3
40					0.1 3.0	0.1 3.4	0.1 4.0	0.1 4.5	0.1 4.6	0.1 4.9	0.1 5.0	0.15 5.0
50						0.1 2.3	0.1 2.9	0.10 3.3	0.10 3.5	0.10 3.7	0.10 3.7	0.10 3.9
64							0.08 1.7	0.08 2.2	0.08 2.5	0.08 2.7	0.08 2.8	0.08 2.9
80								0.07 1.5	0.07 1.7	0.07 2.0	0.07 2.1	0.07 2.2
100									0.05 1.1	0.05 1.5	0.05 1.5	0.05 1.7
125										0.04 0.8	0.04 0.9	0.04 1.2
128												0.04 1.1
160												0.03 0.7
C=1												
N	10	20	30	40	50	60	80	100	120	150	160	200
n	AQL LTPD	AQL LTPD	AQL LTPD	AQL LTPD	AQL LTPD	AQL LTPD	AQL LTPD	AQL LTPD	AQL LTPD	AQL LTPD	AQL LTPD	AQL LTPD
2	27 95	24 95	24 95	23 95	23 95	23 95	23 95	23 95	23 95	22 95	22 95	22 95
4	15 62	12 66	12 66	11 67	11 67	10 67	10 67	10 67	10 67	9.8 67	9.7 67	9.7 68
5	13 51	10 55	8.8 56	8.5 57	8.4 57	8.1 58	7.9 58	7.6 58	7.5 58	7.5 58	7.5 58	7.5 58
8	11 28	7.2 35	6.2 38	5.8 38	5.4 39	5.0 39	4.7 39	4.5 39	4.3 39	4.3 40	4.2 40	4.2 40
10		6.2 30	5.0 30	4.6 31	4.2 32	4.2 32	4.2 32	3.9 33	3.5 33	3.3 33	3.3 33	3.3 33
16		5.6 15	4.2 18	3.8 18	3.4 20	3.0 20	2.9 21	2.6 21	2.5 21	2.3 21	2.3 22	2.2 22
20			4.0 13	3.2 15	2.8 16	2.5 16	2.4 16	2.3 16	2.1 17	2.0 17	2.0 17	2.0 18
25			3.8 9.2	3.1 11	2.5 12	2.2 13	2.0 13	1.8 13	1.7 13	1.6 14	1.6 14	1.6 14
32				3.1 7.4	2.4 8.2	2.1 9.0	1.8 9.9	1.6 10	1.5 10.5	1.4 11	1.3 11	1.3 11
40					2.4 5.9	2.1 6.8	1.6 7.6	1.4 7.8	1.3 8.2	1.2 8.3	1.2 8.4	1.2 8.6
50						1.7 4.6	1.4 5.6	1.2 6.1	1.2 6.4	1.0 6.5	0.9 6.7	0.9 6.7
64							1.3 3.8	1.1 4.4	1.0 4.7	0.8 5.0	0.8 5.0	0.7 5.2
80								1.1 3.0	1.0 3.4	0.8 3.7	0.7 3.8	0.6 4.0
100									0.9 2.5	0.7 2.8	0.7 2.8	0.6 3.0
125										0.7 1.9	0.7 2.0	0.5 2.2
128												0.5 2.2
160										0.7 1.7	0.7 1.9	0.5 1.5
C=2												
N	10	20	30	40	50	60	80	100	120	150	160	200
n	AQL LTPD	AQL LTPD	AQL LTPD	AQL LTPD	AQL LTPD	AQL LTPD	AQL LTPD	AQL LTPD	AQL LTPD	AQL LTPD	AQL LTPD	AQL LTPD
4	33 82	28 83	27 84	27 85	27 85	26 85	26 85	26 86	26 86	25 86	25 86	25 86
5	27 69	23 73	21 74	20 74	20 74	20 75	20 75	19 75	19 75	19 75	19 75	19 75
8	22 42	15 49	14 49	13 52	13 52	13 52	12 53	12 53	12 53	11 53	11 53	11 53
10		13 39	11 42	11 42	10 43	10 43	9.6 43	9.2 44	9.1 44	8.9 44	8.9 44	8.7 44
16		11 22	8.6 25	6.9 27	6.8 27	6.4 27	6.0 28	6.0 29	5.9 29	5.9 29	5.7 29	5.5 30
20			7.7 19	6.2 21	5.9 22	5.6 22	5.1 23	4.8 23	4.8 23	4.6 23	4.5 24	4.5 24
25			7.4 13	6.0 16	4.9 17	4.5 17	4.3 18	4.1 18	3.9 18	3.7 18	3.7 19	3.7 19
32				5.5 11	4.8 12	4.3 13	3.6 14	3.4 14	3.2 14	3.0 14.5	3.0 15	2.9 15
40					4.6 8.9	3.9 9.8	3.1 11	2.8 12	2.6 12	2.4 12	2.4 12	2.3 12
50						3.5 6.9	2.8 8.1	2.4 8.4	2.3 8.6	2.1 9.0	2.1 9.3	2.0 9.5
64							2.6 5.7	2.2 6.2	2.0 6.6	1.8 7.1	1.7 7.1	1.6 7.4
80								2.1 4.5	1.8 4.9	1.6 5.4	1.5 5.4	1.4 5.6
100									1.8 3.5	1.4 3.9	1.4 4.0	1.2 4.4
125										1.4 2.8	1.3 2.9	1.1 3.3
128												1.1 3.2
160										1.4 2.6	1.3 2.9	1.1 2.3



ANNEXE I

This table gives the AQL and LTPD values associated with certain single sampling plans (Acceptance Number "C", Sample Size "n" and Lot Size "N"). The table has the following features:-

- (a) Calculations are based upon the hyper-geometric distribution (exact theory) for lot sizes of 200 devices or less.
- (b) The AQL of a sampling plan is defined as the interpolated Percent Defective for which there is a 0.95 probability of acceptance under the plan. The AQL so defined need not be a realisable Lot Percent Defective for the lot size involved (e.g., 12 percent is not a realisable Percent Defective for a lot size of 20 devices).
- (c) The LTPD of a sampling plan is defined as the interpolated Percent Defective for which there is a 0.10 probability of lot acceptance under the plan. The LTPD so defined need not be a realisable Lot Percent Defective for the lot size involved.
- (d) The sequence of sample sizes and lot sizes are generated by taking products of preceding numbers in the respective sequences and the numbers 2 and 5.